

Robust 5kV RMS Isolated RS-485/RS-422 Transceiver with Level 4 EMC and Full $\pm 42\text{V}$ Protection

FEATURES

- ▶ 5kV rms isolated RS-485 transceiver
- ▶ $\pm 42\text{V}$ AC/DC peak fault protection on RS-485 bus pins
- ▶ DO-160G Section 25 ESD protection: $\pm 15\text{kV}$ air discharge
- ▶ Fully certified DO-160G EMC protection on RS-485 bus pins
 - ▶ Section 22 lightning protection Waveform 3, Waveform 4/ Waveform 1, Waveform 5A Pin injection, Level 4 protection
- ▶ RS-485 A, B pins HBM ESD protection: $> \pm 30\text{kV}$
- ▶ **Safety and regulatory approvals**
 - ▶ DIN EN IEC 60747-17 (VDE 0884-17)
 - ▶ $V_{\text{IORM}} = 849\text{V}$ peak
 - ▶ UL 1577
 - ▶ $V_{\text{ISO}} = 5000\text{V}$ rms for 1 minute
 - ▶ IEC/EN/CSA 60950-1
 - ▶ IEC/CSA 60601-1
 - ▶ IEC/CSA 61010-1
 - ▶ CQC GB 4943.1
- ▶ TIA/EIA RS-485/RS-422 compliant over full supply range
 - ▶ 3V to 5.5V operating voltage range on V_{DD2}
 - ▶ 1.7V to 5.5V operating voltage range on V_{DD1} logic supply
- ▶ Common-mode input range of -25V to $+25\text{V}$
- ▶ High common-mode transient immunity: $> 75\text{kV}/\mu\text{s}$
- ▶ Robust noise immunity (tested to the IEC 62132-4 standard)
- ▶ Passes EN55022 Class B radiated emissions by $6\text{dB}\mu\text{V}/\text{m}$ margin
- ▶ Receiver short-circuit, open-circuit, and floating input fail-safe
- ▶ Supports 256 bus nodes ($96\text{k}\Omega$ receiver input impedance)
- ▶ Glitch free power-up/power-down (hot swap)

ENHANCED PRODUCT FEATURES

- ▶ Supports defense and aerospace applications (AQEC standard)
- ▶ Military -55°C to $+125^\circ\text{C}$ temperature range
- ▶ Controlled manufacturing baseline
- ▶ 1 assembly/test site
- ▶ Enhanced product change notification
- ▶ Qualification data available on request

APPLICATIONS

- ▶ Military and aerospace (MILA) avionics for sensors, actuators, and engine control

GENERAL DESCRIPTION

The ADM2795E-EP is a 5kV rms signal isolated RS-485 transceiver that features up to $\pm 42\text{V}$ of AC/DC peak bus overvoltage fault protection on the RS-485 bus pins. The device integrates Analog Devices, Inc., iCoupler® technology to combine a 3-channel isolator, RS-485 transceiver, and IEC electromagnetic compatibility (EMC) transient protection in a single package. The ADM2795E-EP integrates fully certified DO-160G EMC protection on the RS-485 bus pins, with Section 22 lightning protection. The ADM2795E-EP also provides Section 25 $\pm 15\text{kV}$ ESD air discharge protection. For Section 22 lightning, the ADM2795E-EP provides protection for Waveform 3, Waveform 4/ Waveform 1, and Waveform 5A to Level 4 using 33Ω or 47Ω current limiting resistors to GND_2 , or to Level 4 across the isolation barrier to GND_1 . This device has an extended common-mode input range of $\pm 25\text{V}$ to improve data communication reliability in noisy environments. The ADM2795E-EP is capable of operating over wide power supply ranges, with a 1.7V to 5.5V V_{DD1} power supply range, allowing interfacing to low voltage logic supplies. The ADM2795E-EP is also fully TIA/EIA RS-485/RS-422 compliant when operated over a 3V to 5.5V V_{DD2} power supply. The device is fully characterized over an extended operating temperature range of -55°C to $+125^\circ\text{C}$, and is available in a **16-lead, wide-body SOIC package**.

Additional application and technical information can be found in the [ADM2795E](#) data sheet.

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REVISION HISTORY**4/2026—Rev. 0 to Rev. A**

Changes to Features Section.....	1
Moved Figure 1.....	3
Changes to Specifications Section.....	4
Added Electrical Specifications Section.....	4
Moved Table 1.....	4
Changes to Input Capacitance Parameter, Table 1.....	4
Changed Insulation and Safety Related Specifications Section to Insulation Specifications Section.....	5
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Changes to Figure 2 Caption.....	6
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Changes to Regulatory Information Section and Table 4.....	7
Deleted DIN V VDE V 0884-10 (VDE V 0884-10) Insulation Characteristics Section and Table 6.....	7
Changes to Table 5.....	8
Deleted Table 8.....	8
Added Electrostatic Discharge (ESD) Ratings for ADM2795E-EP Section and Table 7.....	8
Added Electrical Fast Transients (EFT) and Surge Ratings for ADM2795E-EP Section, Table 8, and Table 9.....	8

7/2017—Revision 0: Initial Version

FUNCTIONAL BLOCK DIAGRAM

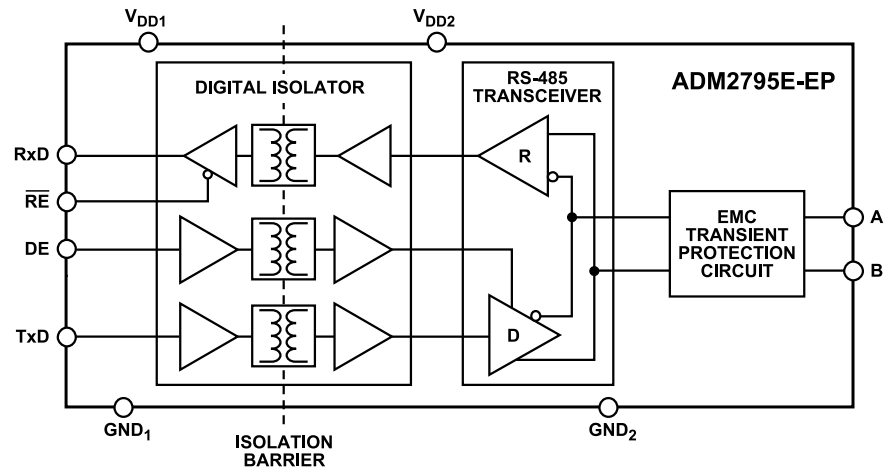


Figure 1. ADM2795E-EP Functional Block Diagram

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SPECIFICATIONS

ELECTRICAL SPECIFICATIONS

$1.7V \leq V_{DD1} \leq 5.5V$, $3V \leq V_{DD2} \leq 5.5V$, $T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$. All min/max specifications apply over the entire recommended operation range, unless otherwise noted. All typical specifications at $T_A = 25^\circ\text{C}$, $V_{DD1} = V_{DD2} = 5.0V$, unless otherwise noted.

Table 1. Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
SUPPLY CURRENT						
Power Supply Current						
Logic Side	I_{DD1}			10	mA	Unloaded output, $DE = V_{DD1}$, $\overline{RE} = 0V$
TxD/RxD Data Rate = 2.5Mbps				10	mA	Unloaded output, $DE = V_{DD1}$, $\overline{RE} = 0V$
Bus Side	I_{DD2}			12	mA	Unloaded output, $DE = V_{DD1}$, $\overline{RE} = 0V$
TxD/RxD Data Rate = 2.5Mbps				90	mA	Unloaded output, $DE = V_{DD1}$, $\overline{RE} = 0V$
				130	mA	$DE = V_{DD1}$, $\overline{RE} = 0V$, $V_{DD2} = 5.5V$, $R = 27\Omega$, see Figure 27
			94		mA	$DE = V_{DD1}$, $\overline{RE} = 0V$, $V_{DD2} = 5.5V$, $R = 27\Omega$, see Figure 27
			46		mA	$DE = V_{DD1}$, $\overline{RE} = 0V$, $V_{DD2} = 3.0V$, $R = 27\Omega$, see Figure 27
Supply Current in Shutdown Mode	I_{SHDN}			10	mA	$DE = 0V$, $\overline{RE} = V_{DD1}$
DRIVER						
Differential Outputs						
Differential Output Voltage	$ V_{OD} $	1.5		5.0	V	$V_{DD2} \geq 3.0V$, $R = 27\Omega$ or 50Ω , see Figure 27
		2.1		5.0	V	$V_{DD2} \geq 4.5V$, $R = 27\Omega$ or 50Ω , see Figure 27
	$ V_{OD3} $	1.5		5.0	V	$V_{DD2} \geq 3.0V$, $V_{CM} = -25V$ to $+25V$, see Figure 28
		2.1		5.0	V	$V_{DD2} \geq 4.5V$, $V_{CM} = -25V$ to $+25V$, see Figure 28
Change in Differential Output Voltage for Complementary Output States	$\Delta V_{OD} $			0.2	V	$R = 27\Omega$ or 50Ω , see Figure 27
Common-Mode Output Voltage	V_{OC}			3.0	V	$R = 27\Omega$ or 50Ω , see Figure 27
Change in Common-Mode Output Voltage for Complementary Output States	$\Delta V_{OC} $			0.2	V	$R = 27\Omega$ or 50Ω , see Figure 27
Short-Circuit Output Current						
$V_{OUT} = \text{Low}$	I_{OSL}	-250		+250	mA	$-42V \leq V_{SC} \leq +42V^1$
$V_{OUT} = \text{High}$	I_{OSH}	-250		+250	mA	$-42V \leq V_{SC} \leq +42V^1$
Logic Inputs (DE, \overline{RE} , TxD)						
Input Threshold Low	V_{IL}			$0.33 \times V_{DD1}$	V	$1.7V \leq V_{DD1} \leq 5.5V$
Input Threshold High	V_{IH}	$0.7 V_{DD1}$			V	$1.7V \leq V_{DD1} \leq 5.5V$
Input Capacitance	C_1		4.0		pF	
Input Current	I_{TXD}			+1	μA	$0V \leq V_{IN} \leq V_{DD1}$
RECEIVER						
Differential Inputs						
Differential Input Threshold Voltage	V_{TH}	-200	-125	-30	mV	$-25V \leq V_{CM} \leq +25V$
Input Voltage Hysteresis	V_{HYS}		30		mV	$-25V \leq V_{CM} \leq +25V$
Input Current (A, B)	I_I	-1.0		+1.0	mA	$DE = 0V$, $V_{DD2} = 0V/5V$, $V_{IN} = \pm 25V$
		-1.0		+1.0	mA	$DE = 0V$, $V_{DD2} = 0V/5V$, $V_{IN} = \pm 42V$
Input Capacitance (A, B)	C_{AB}		150		pF	$T_A = 25^\circ\text{C}$, see Figure 17
Line Input Resistance	R_{IN}	96			k Ω	$-25V \leq V_{CM} \leq +25V$, up to 256 nodes supported
Logic Outputs						
Output Voltage Low	V_{OLRXD}			0.2	V	$I_{ORXD} = 3.0\text{mA}$, $V_A - V_B = -0.2V$
Output Voltage High	V_{OHRXD}	$V_{DD1} - 0.2$			V	$I_{ORXD} = -3.0\text{mA}$, $V_A - V_B = 0.2V$

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Table 1. Electrical Characteristics (Continued)

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
Short-Circuit Current				100	mA	$V_{OUT} = GND$ or V_{DD1} , $\overline{RE} = 0V$
Three-State Output Leakage Current	I_{OZR}			± 2	μA	$\overline{RE} = V_{DD1}$, $RxD = 0V$ or V_{DD1}
COMMON-MODE TRANSIENT IMMUNITY ²		75	125		kV/ μs	$V_{CM} \geq 1kV$, transient magnitude $\geq 800V$

¹ V_{SC} is the short-circuit voltage at the RS-485 A or B bus pin.

² Common-mode transient immunity is the maximum common-mode voltage slew rate that can be sustained while maintaining specification compliant operation. V_{CM} is the common-mode potential difference between the logic and bus sides. The transient magnitude is the range over which the common mode is slewed. The common-mode voltage slew rates apply to both rising and falling common-mode voltage edges.

TIMING SPECIFICATIONS

$V_{DD1} = 1.7V$ to $5.5V$, $V_{DD2} = 3.0V$ to $5.5V$, $T_A = T_{MIN}$ to T_{MAX} ($-55^{\circ}C$ to $+125^{\circ}C$), unless otherwise noted.

Table 2. Timing Characteristics

Parameter	Min	Typ	Max	Unit	Test Conditions/Comments
DRIVER¹					
Maximum Data Rate	2.5			Mbps	
Propagation Delay, t_{DPLH} , t_{DPLH}		30	500	ns	$R_{LDIFF} = 54\Omega$, $C_{L1} = C_{L2} = 100pF$, see Figure 29 and Figure 33
Differential Skew, t_{SKEW}		10	50	ns	$R_{LDIFF} = 54\Omega$, $C_{L1} = C_{L2} = 100pF$, see Figure 29 and Figure 33
Rise/Fall Times, t_R , t_F		40	130	ns	$R_{LDIFF} = 54\Omega$, $C_{L1} = C_{L2} = 100pF$, see Figure 29 and Figure 33
Enable Time, t_{ZH} , t_{ZL}		500	2500	ns	$R_L = 110\Omega$, $C_L = 50pF$, see Figure 30 and Figure 35
Disable Time, t_{HZ} , t_{LZ}		500	2500	ns	$R_L = 110\Omega$, $C_L = 50pF$, see Figure 30 and Figure 35
RECEIVER²					
Propagation Delay, t_{PLH} , t_{PHL}		120	200	ns	$C_L = 15pF$, see Figure 31 and Figure 34, $V_{ID} \geq \pm 1.5V$
		140	220	ns	$C_L = 15pF$, see Figure 31 and Figure 34, $V_{ID} \geq \pm 600mV$
Skew, t_{SKEW}		4	40	ns	$C_L = 15pF$, see Figure 31 and Figure 34, $V_{ID} \geq \pm 1.5V$
Enable Time		10	50	ns	$R_L = 1k\Omega$, $C_L = 15pF$, see Figure 32 and Figure 36
Disable Time		10	50	ns	$R_L = 1k\Omega$, $C_L = 15pF$, see Figure 32 and Figure 36
RxD Pulse Width Distortion			40	ns	$C_L = 15pF$, see Figure 31 and Figure 34, $V_{ID} \geq \pm 1.5V$

¹ See Figure 29 for the definition of R_{LDIFF} .

² Receiver propagation delay, skew, and pulse width distortion specifications are tested with a receiver differential input voltage (V_{ID}) of $\geq \pm 600mV$ or $\geq \pm 1.5V$, as noted.

INSULATION SPECIFICATIONS

The ADM2795E-EP is suitable for "safe electrical insulation" only within the safety limiting ratings. Compliance with the safety limiting ratings shall be ensured by means of suitable protective circuits.

Table 3. ADM2795E-EP 16-Lead Standard Small Outline Package [SOIC_W] (RW-16) Insulation Characteristics

Parameter	Symbol	Value	Unit	Test Conditions/Comments
GENERAL				
Minimum External Clearance Distance	CLR	7.8	mm	Measured from input terminals to output terminals, shortest distance through air per IEC 60664-1
Minimum External Creepage Distance	CRP	7.8	mm	Measured from input terminals to output terminals, shortest distance along body per IEC 60664-1
Distance Through Insulation	DTI	29.0	μm	Minimum internal
Comparative Tracking Index	CTI	>400	V	Per IEC 60112
Material Group		II		Per IEC 60664-1
Overtoltage Category per IEC 60664-1		I to IV		Rated mains voltage $\leq 300V$ rms
		I to III		Rated mains voltage $\leq 400V$ rms

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Table 3. ADM2795E-EP 16-Lead Standard Small Outline Package [SOIC_W] (RW-16) Insulation Characteristics (Continued)

Parameter	Symbol	Value	Unit	Test Conditions/Comments
SAFETY LIMITING VALUES				
Maximum Ambient Safety Temperature	T_S	150	°C	
Maximum Total Power Dissipation	P_{TOT}	1.8	W	$T_A \leq 25^\circ\text{C}$, $P_{TOT} = P_{SI} = P_{SO}$
Derating Above Ambient (T_A)		14.4	mW/°C	$T_A > 25^\circ\text{C}$, see Figure 2
Junction-to-Air Thermal Impedance	θ_{JA}	59.7	°C/W	See the Thermal Resistance section
IEC 60747-17 (REINFORCED INSULATION)				
Maximum Repetitive Peak Isolation Voltage	V_{IORM}	849	V peak	
Maximum Isolation Working Voltage	V_{IOWM}	600	V rms	AC voltage, end of life test, $f = 60\text{Hz}$
		849	V peak	DC voltage
Maximum Transient Isolation Voltage	V_{IOTM}	7000	V peak	$V_{TEST} \geq 1.2 \times V_{IOTM}$, $t = 1\text{s}$ (100% production)
Maximum Impulse Voltage	V_{IMP}	7000	V peak	Surge voltage in air, waveform per IEC 61000-4-5
Maximum Surge Isolation Voltage	V_{IOSM}	12800	V peak	$V_{TEST} \geq 1.3 \times V_{IMP}$ minimum 10kV (type test), tested in oil, waveform per IEC 61000-4-5
Apparent Charge	q_{pd}	≤ 5	pC	Method a (sample test), $V_{ini} = V_{IOTM}$, $t_{ini} = 60\text{s}$, $V_{pd(m)} = 1.6 \times V_{IORM}$, $t_m = 10\text{s}$ Method b1 (100% production), $V_{ini} \geq 1.2 \times V_{IOTM}$, $t_{ini} = 1\text{s}$, $V_{pd(m)} = 1.875 \times V_{IORM}$, $t_m = 1\text{s}$
Resistance (Input to Output) ¹	R_{IO}	$>10^{13}$	Ω	$T_A = 25^\circ\text{C}$, $V_{TEST} = 500\text{V DC}$, $t = 60\text{s}$
	R_{IO_S}	$>10^9$	Ω	$T_A = T_S$, $V_{TEST} = 500\text{V DC}$, $t = 60\text{s}$
Capacitance (Input to Output) ¹	C_{IO}	2.2	pF	$f_{TEST} = 1\text{MHz}$
Climatic Category		55/125/21		
Pollution Degree		2		Per IEC 60664-1
UL 1577				
Maximum Withstanding Isolation Voltage	V_{ISO}	5000	V rms	$V_{TEST} = 1.2 \times V_{ISO}$, $t = 1\text{s}$ (100% production)

¹ Device measured as a 2-terminal device with Pin 1 to Pin 8 connected and Pin 9 to Pin 16 connected.

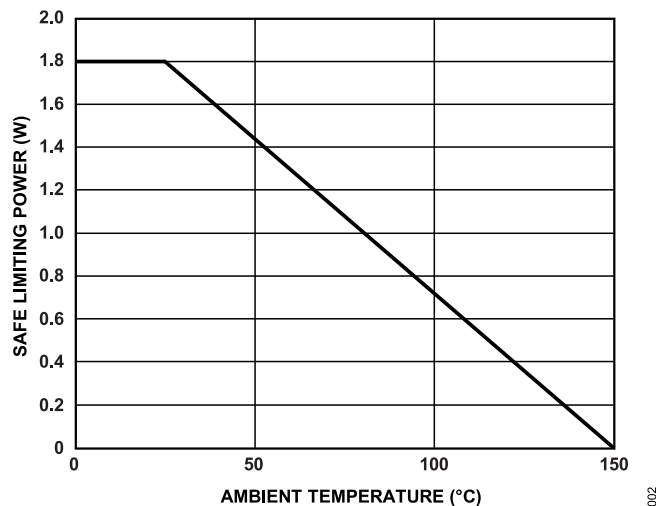


Figure 2. Thermal Derating Curve for 16-Lead Standard Small Outline Package [SOIC_W] (RW-16) Package, Dependence of Safety Limiting Power with Ambient Temperature per IEC 60747-17

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REGULATORY INFORMATION

The ADM2795E-EP has been approved by the organizations listed in [Table 4](#). Copies of the relevant certificates are available at [Safety and Regulatory Certifications for Digital Isolation](#).

Table 4. ADM2795E-EP 16-Lead Standard Small Outline Package [SOIC_W] (RW-16) Package Certifications

Regulatory Agency	Safety Standard/Rating	File or Certificate Number
UL	UL 1577 Single protection, 5000V rms isolation voltage	File E214100
CSA ¹	CSA/EN/IEC 60950-1 Basic insulation at 780V rms Reinforced insulation at 390V rms CSA/IEC 60601-1 2 MOPP at 237.5V rms CSA/IEC 61010-1 Basic insulation at 600V rms ²	File 205078
VDE	DIN EN IEC 60747-17 (VDE 0884-17) Reinforced insulation at 849V peak	Certificate 40051926
CQC	GB 4943.1 Basic insulation at 780V rms Reinforced insulation at 390V rms	Certificate CQC18001204896

¹ Working voltages are quoted for Pollution Degree 2, Material Group III and Overvoltage Category II except where otherwise specified. The ADM2795E-EP case material has been evaluated by CSA as Material Group II.

² Overvoltage Category III.

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 5.

Parameter	Rating
V_{DD1}	-0.5V to +7V
V_{DD2}	-0.5V to +7V
Digital Input/Output Voltage (DE, $\overline{\text{RE}}$, TxD, RxD)	-0.3V to $V_{DD1} + 0.3\text{V}$
Driver Output/Receiver Input Voltage	$\pm 48\text{V}$
Operating Temperature Range	-55°C to $+125^\circ\text{C}$
Storage Temperature Range	-65°C to $+150^\circ\text{C}$
Maximum Junction Temperature	150°C
Continuous Total Power Dissipation	405mW
Lead Temperature	
Soldering (10 sec)	300°C
Vapor Phase (60 sec)	215°C
Infrared (15 sec)	220°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Thermal performance is directly linked to PCB design and operating environment. Careful attention to PCB thermal design is required.

θ_{JA} is the natural convection junction to ambient thermal resistance measured in a one cubic foot sealed enclosure. θ_{JC} is the junction to case thermal resistance.

Table 6. Thermal Resistance

Package Type	θ_{JA} ¹	θ_{JC} ¹	Unit
RW-16	59.7	28.3	$^\circ\text{C}/\text{W}$

¹ Thermal impedance simulated values are based on a JEDEC 2S2P thermal test board with no vias. See JEDEC JESD51.

ELECTROSTATIC DISCHARGE (ESD) RATINGS FOR ADM2795E-EP

The following ESD information is provided for handling of ESD-sensitive devices in an ESD-protected area only.

Human body model (HBM) per ANSI/ESDA/JEDEC JS-001.

Charged device model (CDM) per ANSI/ESDA/JEDEC JS-002.

International Electrotechnical Commission (IEC) electromagnetic compatibility: Part 4-2 (IEC) per IEC 61000-4-2.

Air Discharge (DO-160G) per DO-160G Section 25 ESD Protection.

Table 7. ADM2795E-EP, 16-Lead Standard Small Outline Package [SOIC_W] (RW-16) ESD Characteristics

ESD Model	Withstand Threshold (kV)	Class
HBM	$\geq \pm 6$	3A ¹
	$> \pm 30$	3B ²
CDM	± 1.250	C5 ¹
IEC	± 8 (contact) to GND ₂	Level 4 ²
	± 15 (air) to GND ₂	Level 4 ²
	± 9 (contact) to GND ₁	Level 4 ^{2,3}
	± 8 (air) to GND ₁	Level 3 ^{2,3}
DO-160G	± 15 (air) ²	

¹ All pins.

² Pin A and Pin B only.

³ Limited by clearance across isolation barrier.

ELECTRICAL FAST TRANSIENTS (EFT) AND SURGE RATINGS FOR ADM2795E-EP

International Electrotechnical Commission (IEC) electromagnetic compatibility: Part 4-4 (IEC) per IEC 61000-4-4.

Table 8. ADM2795E-EP, 16-Lead Standard Small Outline Package [SOIC_W] (RW-16) EFT Characteristics

Model	Withstand Threshold (kV)	Repetition Frequency (kHz)	Class
IEC	± 2 to GND ₂	5 or 100	Level 4 ¹
	± 2 to GND ₁	5 or 100	Level 4 ¹

¹ Pin A and Pin B only.

International Electrotechnical Commission (IEC) electromagnetic compatibility: Part 4-5 (IEC) per IEC 61000-4-5.

Table 9. ADM2795E-EP, 16-Lead Standard Small Outline Package [SOIC_W] (RW-16) Surge Characteristics

Model	Withstand Threshold (kV)	Class
IEC	± 4 to GND ₂	Level 4 ¹
	± 4 to GND ₁	Level 4 ¹

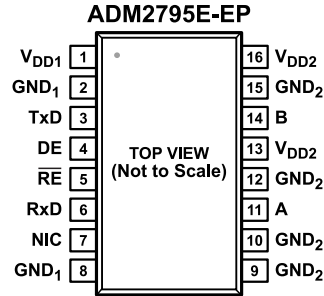
¹ Pin A and Pin B only.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



NOTES
 1. NIC = NOT INTERNALLY CONNECTED. 00

Figure 3. Pin Configuration

Table 10. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	V _{DD1}	1.7V to 5.5V Flexible Logic Interface Supply.
2	GND ₁	Ground 1, Logic Side.
3	TxD	Transmit Data Input. Data to be transmitted by the driver is applied to this input.
4	DE	Driver Output Enable. A high level on this pin enables the driver differential outputs, A and B. A low level places them into a high impedance state.
5	RE	Receiver Enable Input. This pin is an active low input. Driving this input low enables the receiver, and driving it high disables the receiver.
6	RxD	Receiver Output Data. This output is high when (A – B) > –30mV and low when (A – B) < –200mV.
7	NIC	Not Internally Connected. This pin is not internally connected.
8	GND ₁	Ground 1, Logic Side.
9	GND ₂	Isolated Ground 2, Bus Side.
10	GND ₂	Isolated Ground 2, Bus Side.
11	A	Noninverting Driver Output/Receiver Input. When the driver is disabled, or when V _{DD1} or V _{DD2} is powered down, Pin A is put into a high impedance state to avoid overloading the bus.
12	GND ₂	Isolated Ground 2, Bus Side.
13	V _{DD2}	3V to 5.5V Power Supply. Pin 13 must be connected externally to Pin 16.
14	B	Inverting Driver Output/Receiver Input. When the driver is disabled, or when V _{DD1} or V _{DD2} is powered down, Pin B is put into a high impedance state to avoid overloading the bus.
15	GND ₂	Isolated Ground 2, Bus Side.
16	V _{DD2}	3V to 5.5V Power Supply. Pin 16 must be connected externally to Pin 13.

TYPICAL PERFORMANCE CHARACTERISTICS

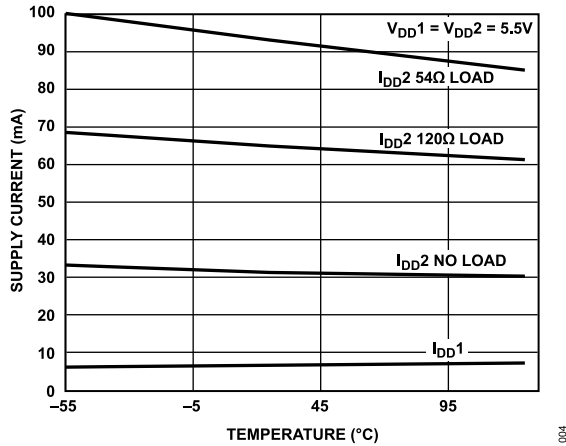


Figure 4. Supply Current (I_{CC}) vs. Temperature at $R_L = 54\Omega$, 120Ω , and No Load; Data Rate = 2.5Mbps, $V_{DD1} = 5.5V$, $V_{DD2} = 5.5V$

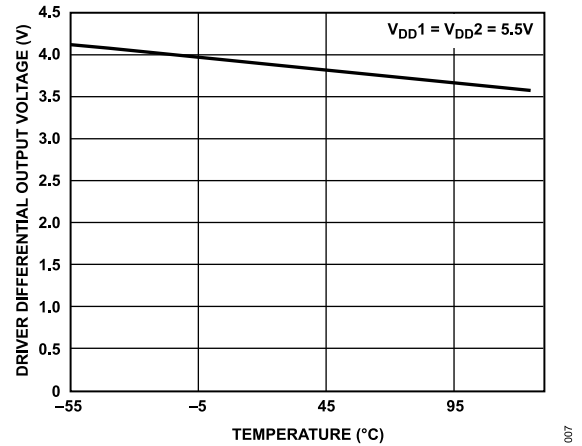


Figure 7. Driver Differential Output Voltage vs. Temperature

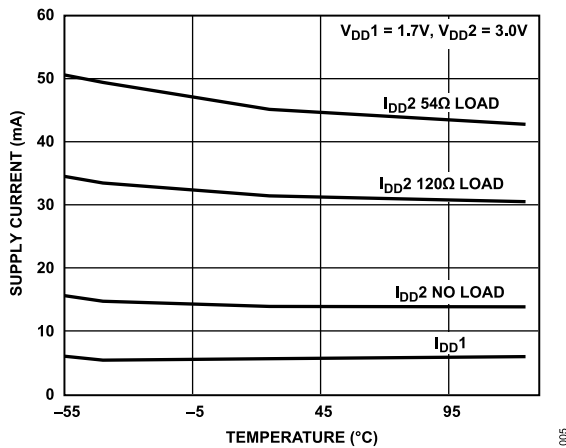


Figure 5. Supply Current (I_{CC}) vs. Temperature at $R_L = 54\Omega$, 120Ω , and No Load; Data Rate = 2.5Mbps, $V_{DD1} = 1.7V$, $V_{DD2} = 3.0V$

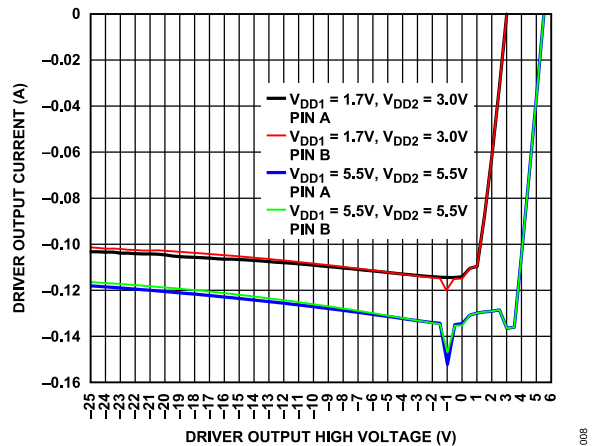


Figure 8. Driver Output Current vs. Driver Output High Voltage

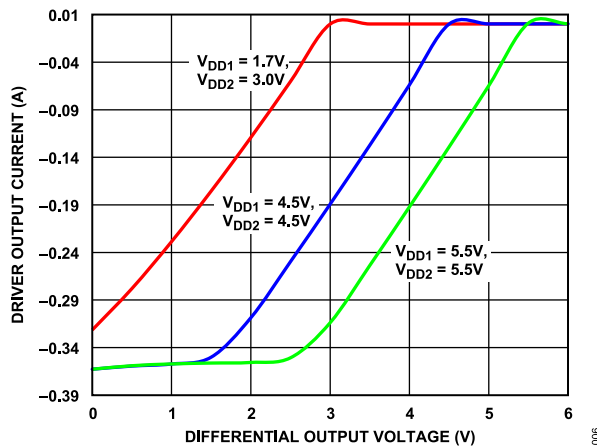


Figure 6. Driver Output Current vs. Differential Output Voltage

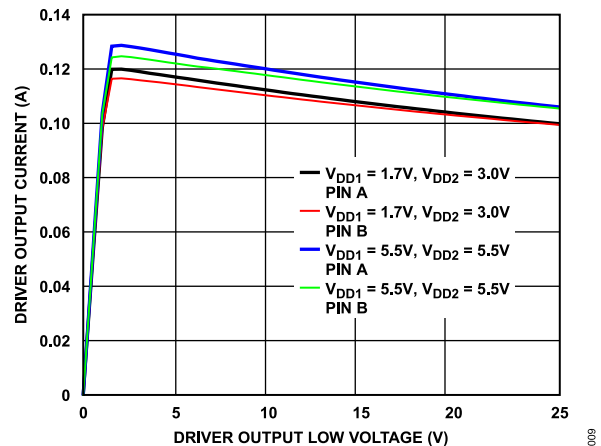


Figure 9. Driver Output Current vs. Driver Output Low Voltage

TYPICAL PERFORMANCE CHARACTERISTICS

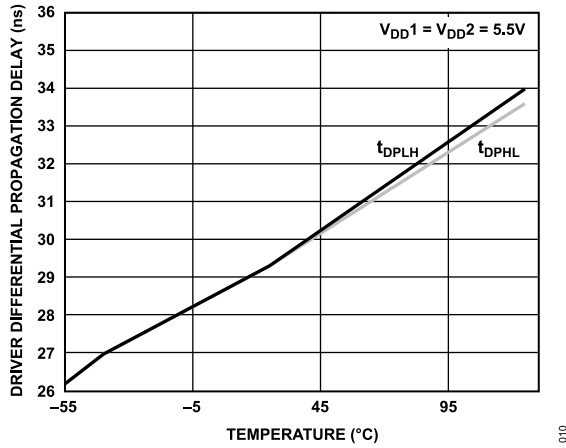


Figure 10. Driver Differential Propagation Delay vs. Temperature

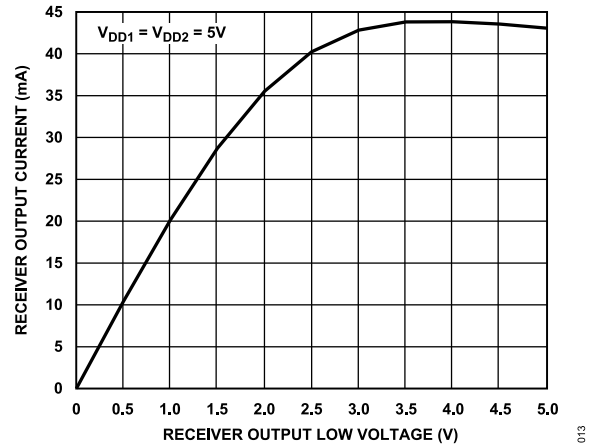


Figure 13. Receiver Output Current vs. Receiver Output Low Voltage

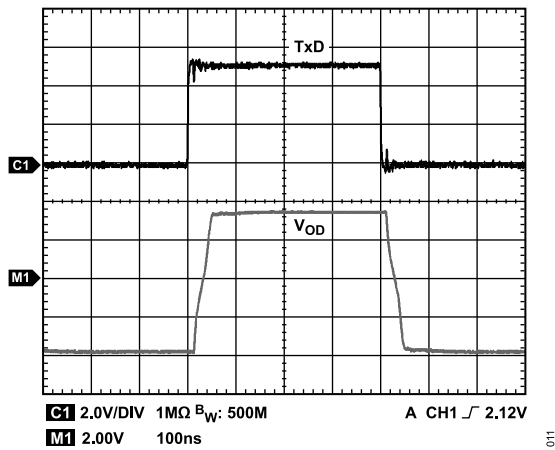


Figure 11. Driver Propagation Delay (Oscilloscope)

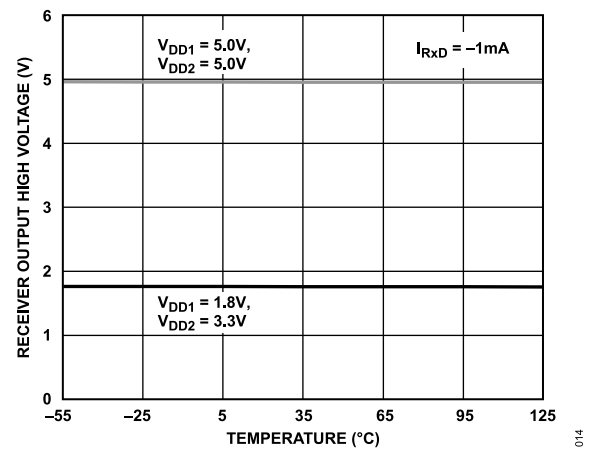


Figure 14. Receiver Output High Voltage vs. Temperature

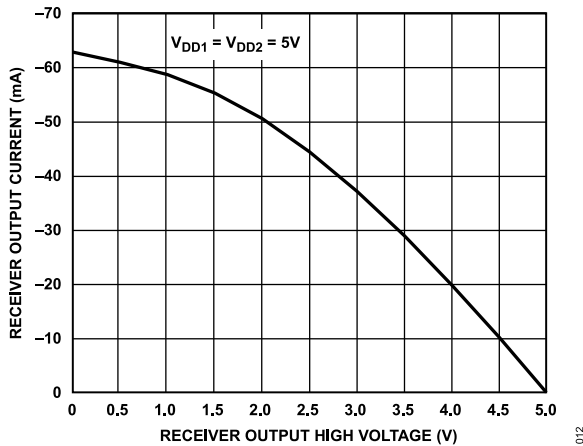


Figure 12. Receiver Output Current vs. Receiver Output High Voltage

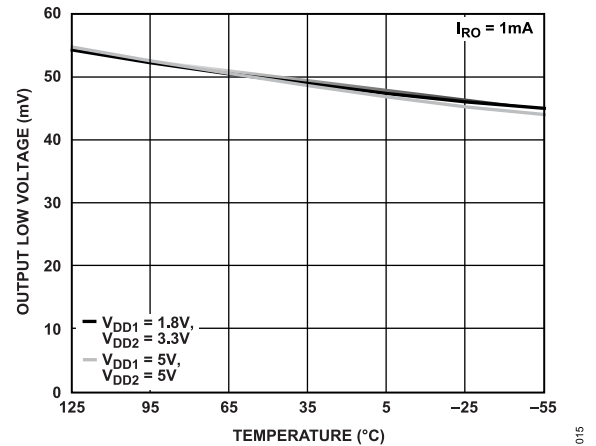


Figure 15. Receiver Output Low Voltage vs. Temperature

TYPICAL PERFORMANCE CHARACTERISTICS

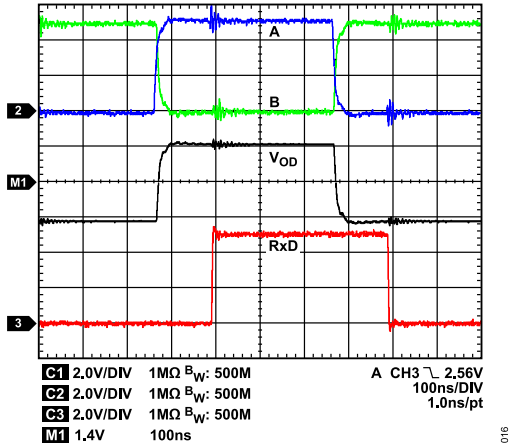


Figure 16. Receiver Propagation Delay (Oscilloscope)

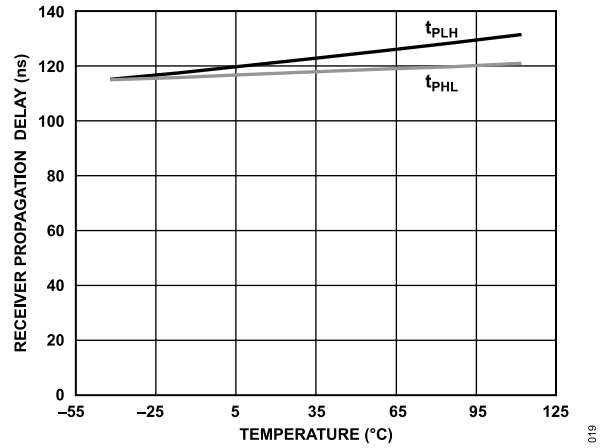


Figure 19. Receiver Propagation Delay vs. Temperature

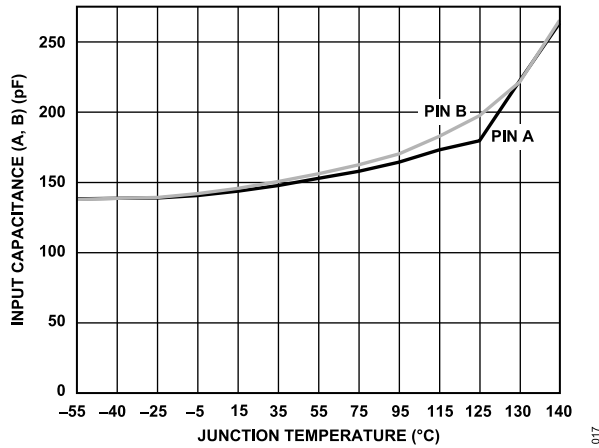


Figure 17. Input Capacitance (A, B) vs. Junction Temperature

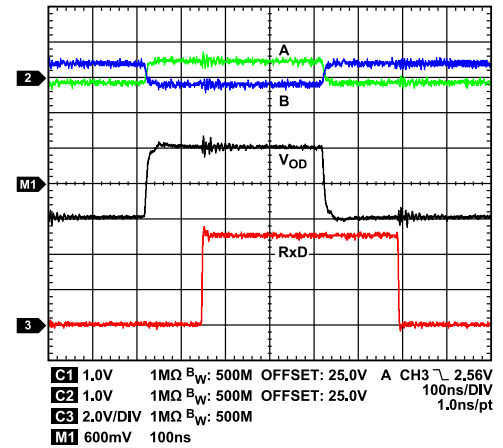


Figure 20. Receiver Performance with Input Common-Mode Voltage of 25V

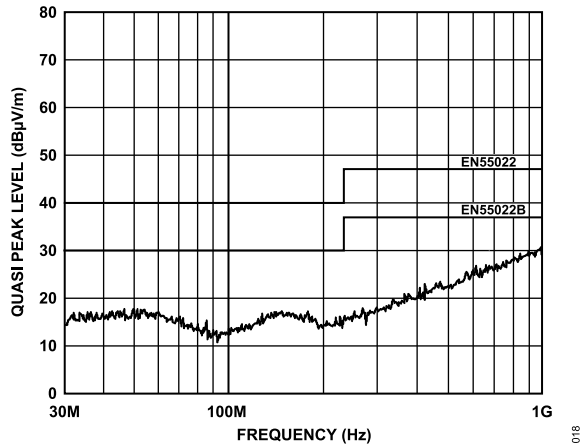


Figure 18. Radiated Emissions Profile with 120pF Capacitor to GND₁ on the RxD Pin (Horizontal Scan, Data Rate = 2.5Mbps, V_{DD1} = V_{DD2} = 5.0V)

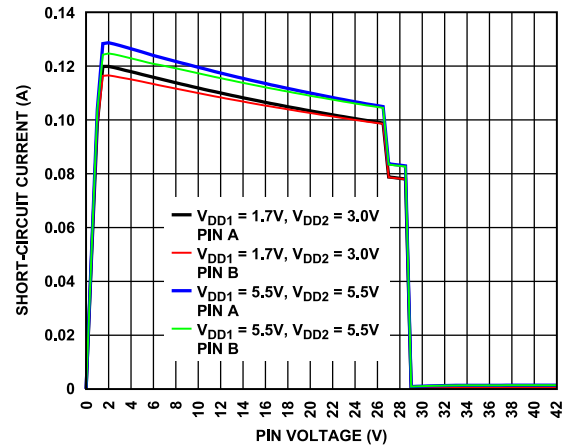


Figure 21. Short-Circuit Current over Fault Voltage Range

TYPICAL PERFORMANCE CHARACTERISTICS

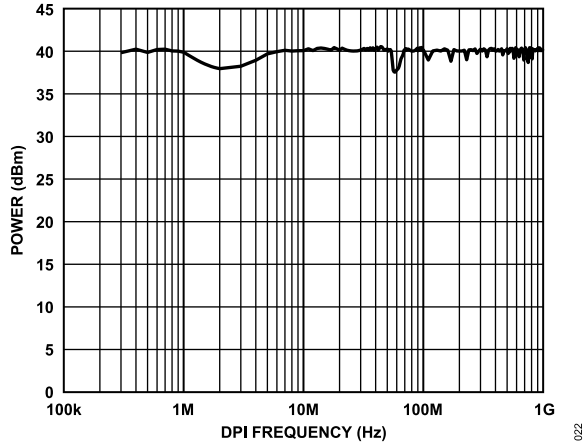


Figure 22. DPI IEC 62132-4 Noise Immunity with 100nF and 10µF Decoupling on V_{DD1}

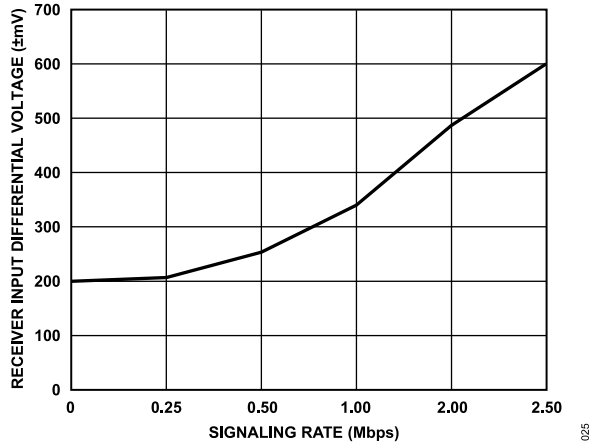


Figure 25. Receiver Input Differential Voltage (V_{ID}) vs. Signaling Rate

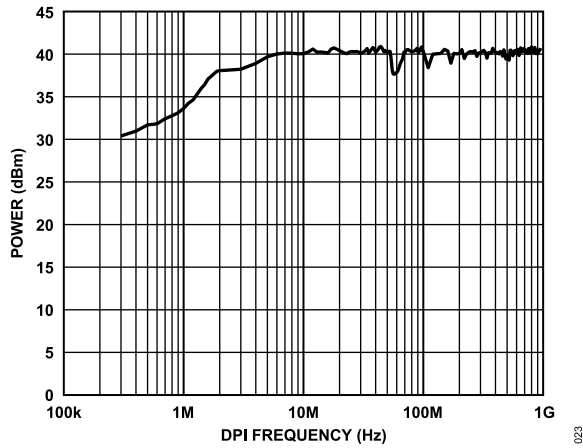


Figure 23. DPI IEC 62132-4 Noise Immunity with 100nF Decoupling on V_{DD1}

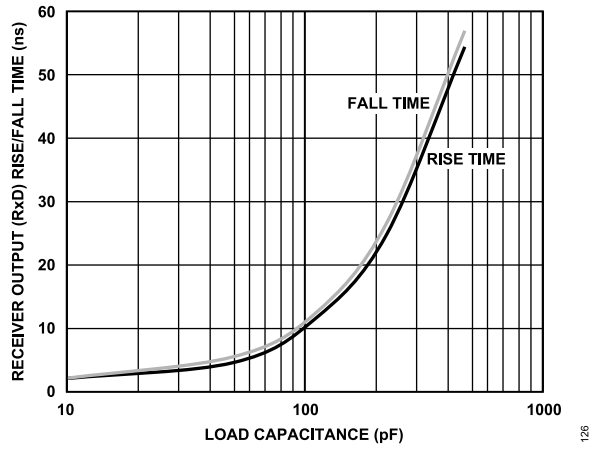


Figure 26. Receiver Output (RxD) Rise/Fall Time vs. Load Capacitance

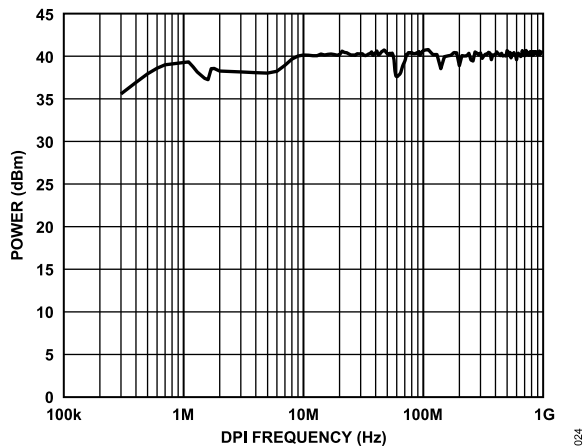


Figure 24. DPI IEC 62132-4 Noise Immunity with 100nF and Decoupling on V_{DD2}

TEST CIRCUITS

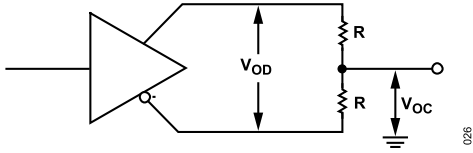


Figure 27. Driver Voltage Measurement

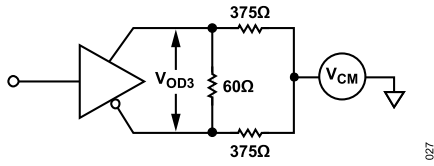


Figure 28. Driver Voltage Measurement over Common-Mode Voltage Range

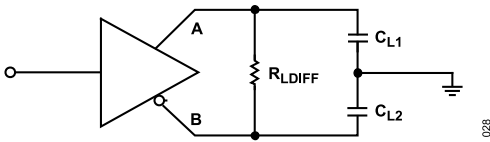


Figure 29. Driver Propagation Delay

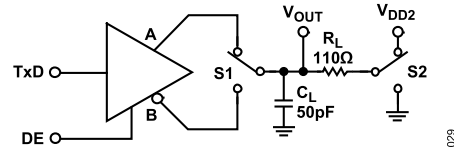


Figure 30. Driver Enable/Disable

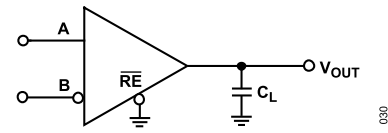


Figure 31. Receiver Propagation Delay

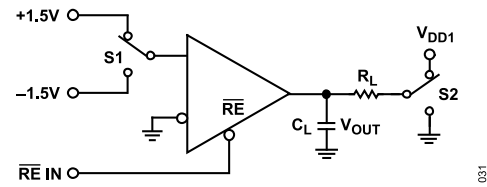


Figure 32. Receiver Enable/Disable

TEST CIRCUITS

SWITCHING CHARACTERISTICS

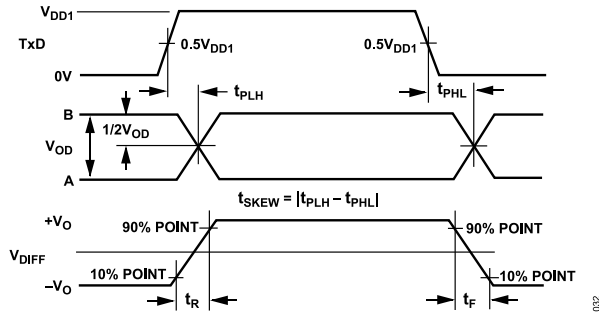


Figure 33. Driver Propagation Delay, Rise/Fall Timing

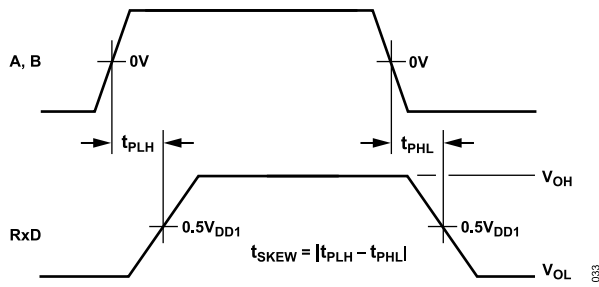


Figure 34. Receiver Propagation Delay

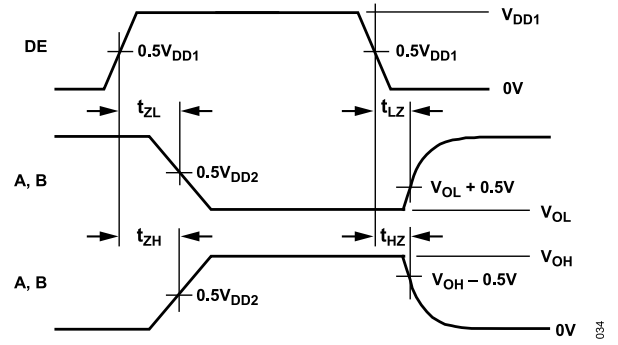


Figure 35. Driver Enable/Disable Timing

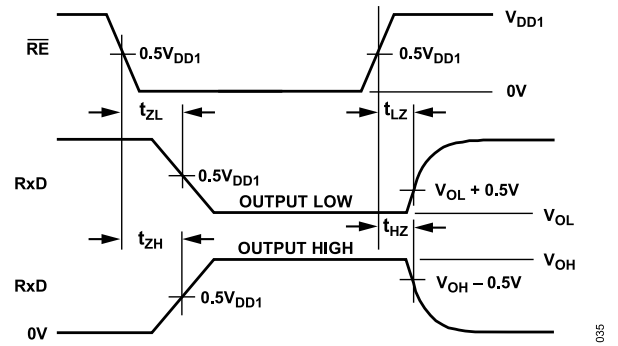


Figure 36. Receiver Enable/Disable Timing

THEORY OF OPERATION

RS-485 WITH ADDED DO-160G EMC ROBUSTNESS

The ADM2795E-EP is a 3V to 5.5V RS-485 transceiver with added robustness that reduces system failures when operating in harsh application environments such as military and aerospace (MILA) avionics for sensors, actuators, and engine control.

Lightning strikes to jet airliners are common, about once every 1000 flight hours. The DO-160G standard, *Environmental Conditions and Test Procedures for Airborne Equipment*, is a standard for the environmental testing of avionics hardware. Many airplane manufacturers specify DO-160G Section 22, lightning induced transient susceptibility, as a requirement for critical systems, like guidance, radars, communications, engine control, and heat and air controls. Aircraft radome, wing tips, fin tips, nacelles, and landing gear are areas most likely to be hit by lightning strikes.

The ADM2795E-EP integrates fully certified DO-160G EMC protection on the RS-485 bus pins, with Section 22 lightning protection. The ADM2795E-EP also provides Section 25 ±15kV ESD air discharge protection. For Section 22 lightning, the ADM2795E-EP provides protection against Waveform 3, Waveform 4/Waveform 1, and Waveform 5A to Level 4 using 33Ω or 47Ω current limiting resistors to GND₂, or to Level 4 across the isolation barrier to GND₁.

CERTIFIED DO-160G EMC PROTECTION

Table 11 details the open circuit voltage (V_{OC}) and short-circuit current (I_{SC}) as specified in the DO-160G Section 22 lightning induced transient susceptibility standard for Waveform 3, Waveform 4/Waveform 1, and Waveform 5A for pin injection testing. The peak currents for the DO-160G Level 4 tests are much greater than standard industrial surge IEC 61000-4-5 peak currents. The waveform shape and rise/decay times for the DO-160G standard are significantly longer than those specified by the IEC 61000-4-5 standard, as shown in Figure 37. Due to the high amounts of

energy associated with the DO-160G Section 22 lightning standard, the ADM2795E-EP was tested using external 33Ω or 47Ω A pin and B pin bus current limiting resistors for testing to GND₂. These resistors were required in addition to the ADM2795E-EP integrated EMC protection circuitry. However, when testing to GND₁, no current limiting resistors are required. The ADM2795E-EP iCoupler isolation technology protects the device in the presence of these extreme transients.

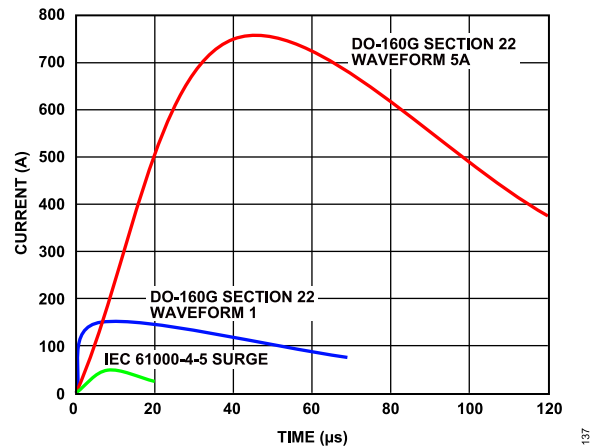


Figure 37. DO-160G Section 22 Waveform 1 and Waveform 5A, and IEC61000-4-5 Surge Waveform

DO-160G ADM2795E-EP TEST DETAILS

Figure 38 and Figure 39 show the Waveform 3 test setup coupling/decoupling network (CDN) and the Waveform 5A, Waveform 4/Waveform 1 CDN, respectively. For testing to RS-485 bus side, GND₂, an additional 33Ω or 47Ω current limiting resistance is added on both A and B bus pins. DO-160G Section 22 testing is performed on one pin at a time. The test is not performed in common mode. Table 12 and Table 13 show a summary of the ADM2795E-EP certified test results.

Table 11. DO-160G Section 22 Pin Injection Level 4 and Level 3 Compared to IEC 61000-4-5 Lightning Level 4 and Level 3

Level	DO-160G Waveform 3	DO-160G Waveform 4/Waveform 1	DO-160G Waveform 5A	IEC 61000-4-5
4	1500V, 60A	750V, 150A	750V, 750A	4000V, 49A
3	600V, 24A	300V, 60A	300V, 300A	2000V, 24.5A

Table 12. DO-160G Section 22 Pin Injection Level 4 Certified Test Results

Testing to GND _x	Current Limiting Resistor	DO-160 Waveform 3; 1500V, 60A	DO-160 Waveform 4/ Waveform 1; 750V, 150A	DO-160 Waveform 5A; 750V ,750A
GND ₁	None	Pass	Pass	Pass
GND ₂	47Ω or 33Ω	Pass with 47Ω	Pass with 33Ω	Pass with 33Ω

Table 13. DO-160G Section 22 Pin Injection Level 3 Certified Test Results

Testing to GND _x	Current Limiting Resistor	DO-160 Waveform 3; 600V, 24A	DO-160 Waveform 4/ Waveform 1; 300V, 60A	DO-160 Waveform 5A; 300V ,300A
GND ₁	None	Pass	Pass	Pass
GND ₂	33Ω	Pass	Pass	Pass

THEORY OF OPERATION

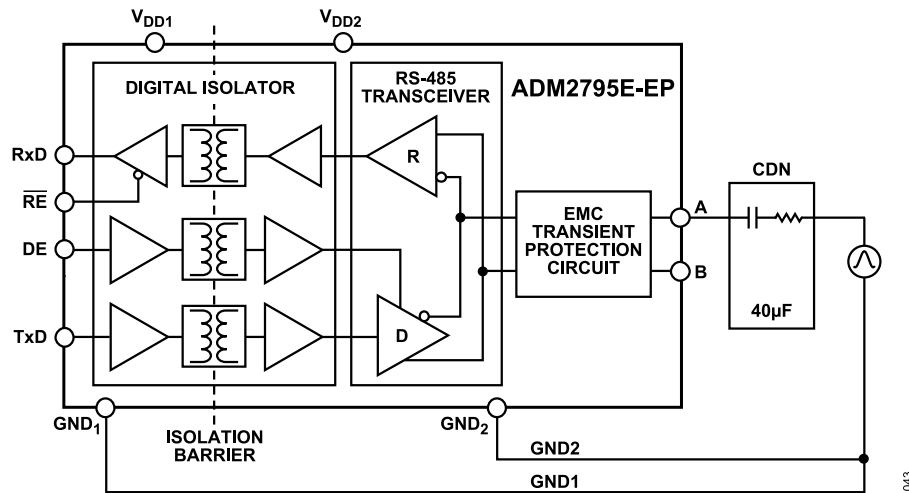


Figure 38. DO-160G Section 22 Waveform 3 Test Setup CDN

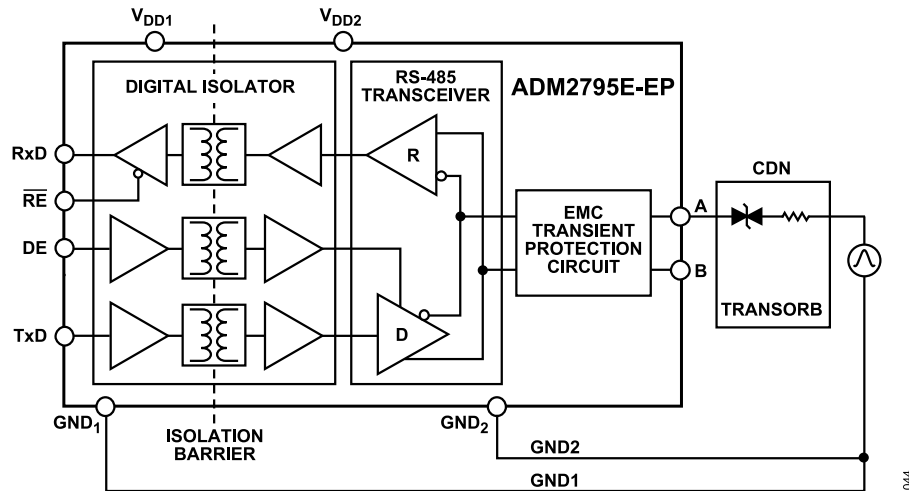
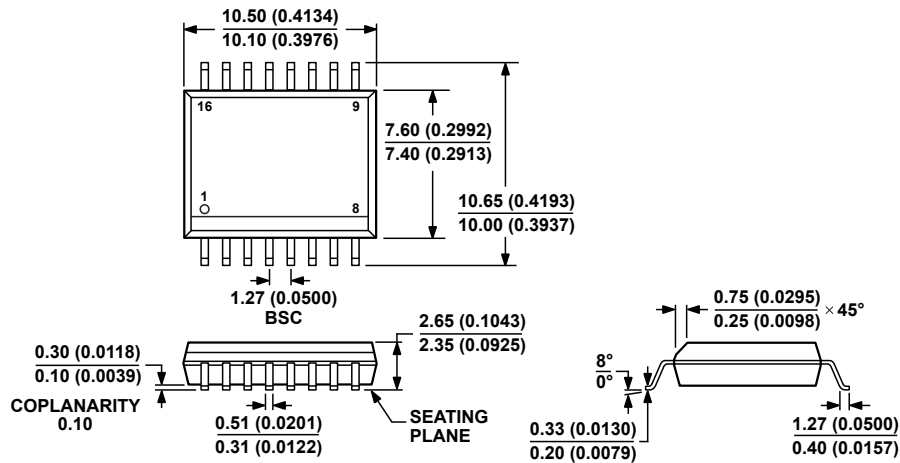


Figure 39. DO-160G Section 22 Waveform 5A, Waveform 4/Waveform 1 Test Setup CDN

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MS-013-AA
 CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
 (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
 REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

00-27-2007-B

Figure 40. 16-Lead Standard Small Outline Package [SOIC_W]
 Wide Body
 (RW-16)
 Dimensions shown in millimeters and (inches)

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Packing Quantity	Package Option
ADM2795ETRZW-EP	-55°C to +125°C	16-Lead Standard Small Outline Package [SOIC_W]	Tube, 47	RW-16
ADM2795ETRZW-EP-R7	-55°C to +125°C	16-Lead Standard Small Outline Package [SOIC_W], 7" Reel	Reel, 400	RW-16

¹ Z = RoHS Compliant Part.

EVALUATION BOARDS

Model ¹	Description
EVAL-ADM2795EEPZ	Evaluation Board

¹ Z = RoHS Compliant Part.

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